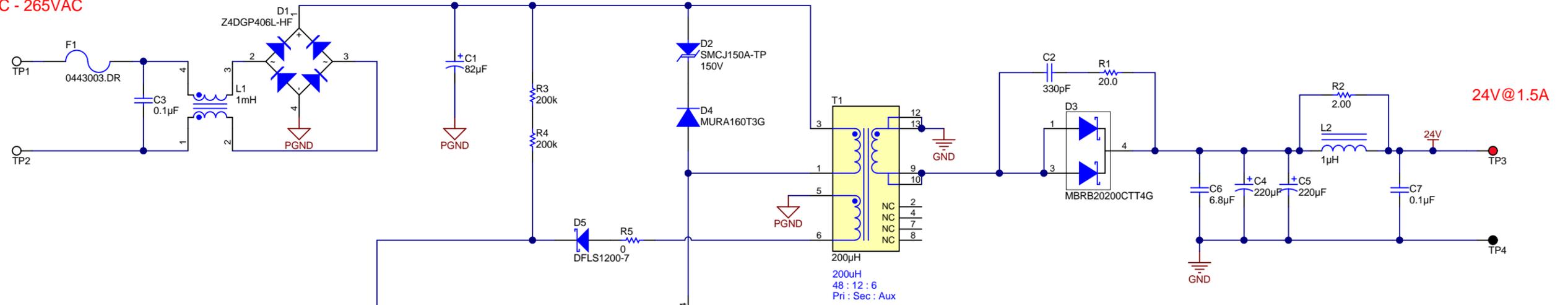
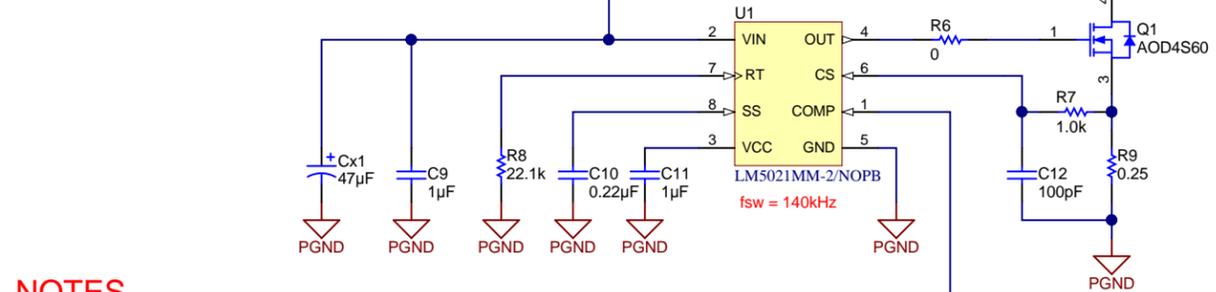


85VAC - 265VAC

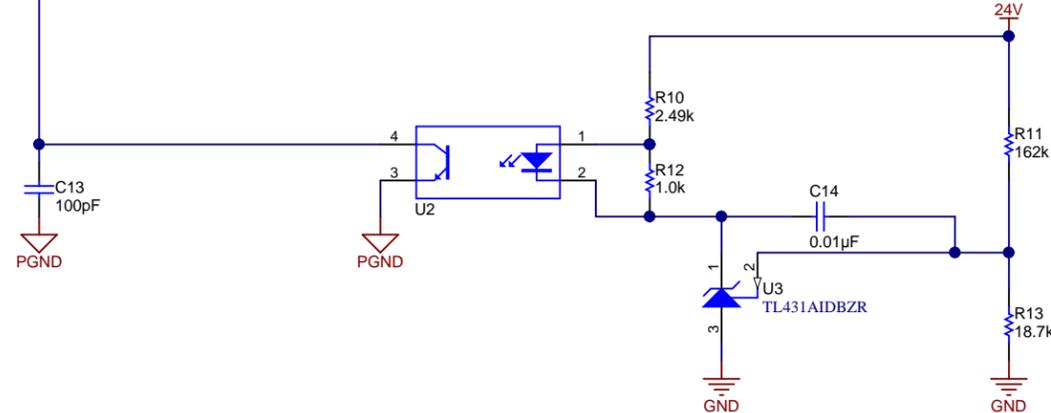


24V@1.5A



NOTES

- 1) D2 Replaced with SMCJ140 during Test
- 2) Cx1: EEU-FC1V470 is needed and was placed in parallel with C9 during Test
- 3) C2 and R1 snubber is needed and was populated during test



Orderable: ChangeMe!	Designed for: Public Release	Mod. Date: 4/18/2017	TEXAS INSTRUMENTS
TID #: N/A	Project Title: 85VAC-265VAC to 24V@1.5A DCM Flyback using L	Sheet: 1 of 1	
Number: PMP20809	Rev: A	File: PMP20809_Sheet1.SchDoc	Size: B
SVN Rev: Version control disabled	Engineer: C Sarli	Contact: http://www.ti.com/support	http://www.ti.com

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